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Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T
WL	3.	Solomon "Providing High Density and Performance for Chip-to System Interconnection" Advanced Packaging (November 2001) pp 19-28	
WL	4.	Yung et al; "Flip-Chip Process Utilizing Electroplated Solder Joints"; Proceedings of the Technical Conference, (Sep. 10-12, 1990) International Electronics Packaging Conference Malborough, Massachusetts pp1065-1073	
Examiner Signature		William Leader	Date Considered 6/21/93

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.